



PRODUCT INFORMATION LETTER

PIL IPD-DIS/13/8034
Dated 29 Jul 2013

**SO8 Super High Density leadframe qualification in ST
in-house plant (China)**

Sales Type/product family label	ACS102-6T1-TR
Type of change	Package assembly process change
Reason for change	To increase its industrial capacity
Description	Implementation of Super High Density frame on products housed in SO8 package. -The changed products do not present modified electrical, dimensional or thermal parameters, leaving unchanged the current information published in the product datasheet -The Moisture Sensitivity Level of the part (according to the IPC/JEDEC JSTD-020D standard) remains unchanged. -The footprint recommended by ST remains the same. -There is no change neither in the packing modes nor the standard delivery quantities.
Forecasted date of implementation	22-Aug-2013
Forecasted date of samples for customer	22-Jul-2013
Forecasted date for STMicroelectronics change Qualification Plan results availability	22-Jul-2013
Involved ST facilities	ST in-house plant (China)

DOCUMENT APPROVAL

Name	Function
Paris, Eric	Marketing Manager
Duclos, Franck	Product Manager
Cazaubon, Guy	Q.A. Manager

PIL

Product/Process Information Letter

SO8 Super High Density leadframe qualification in ST in-house plant (China)

Notification number:	IPD-DIS/13/8034	Issue Date	22/07/2013
Issued by	Aline AUGIS		
Product series affected by the change	ACS102-6T1-TR		

Reason for change

ST upgrades its products housed in SO8 package with a new Super High Density frame in order to increase its industrial capacity.

Effects of change

Implementation of Super High Density frame on products housed in SO8 package.

- The changed products do not present modified electrical, dimensional or thermal parameters, leaving unchanged the current information published in the product datasheet
- The Moisture Sensitivity Level of the part (according to the IPC/JEDEC JSTD-020D standard) remains unchanged.
- The footprint recommended by ST remains the same.
- There is no change neither in the packing modes nor the standard delivery quantities .

Product identification and traceability

Traceability and identification is ensured by:

- Specific **internal product codification** for devices with Super High Density leadframe. This code is mentioned on the inner and outer packing box.
- **QA lot number** .

Qualification complete date	8 th of April, 2013
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Forecasted sample availability

Product family	Package	Commercial part Number	Availability date
Thyristors (SCR) and AC Switches	SO8	ACS102-6T1-TR	Now

Change implementation schedule

Sales types	Estimated production start	Estimated first shipments
ACS102-6T1-TR	Week 28-2013	Week 34-2013



Public Products List

PIL Title : SO8 Super High Density leadframe qualification in ST in-house plant (China)

PIL Reference : IPD-DIS/13/8034

PIL Created on : 31-JUL-2013

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change:

ST COMMERCIAL PRODUCT

ACS102-6T1-TR

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